Vibgyorlighting

SOLDERING **MATERIALS**

PRODUCT CATALOG

WIRE / BARS / PASTE

For electronic assembly
and industrial soldering.



SOLDER WIRE



LEAD-FREE PASTE



SOLDER BARS



TIN-LEAD PASTE

Vibgyorlighting-Shanghai Vibgyor Intelligence Technology Co.,Ltd
Phone: 0086 15026859051 | Email: info@electricalvibgyor.com

01 / PRODUCT RANGE

Choose your material.



Solder wire 03-04

Lead-free / Tin-lead



Solder bars 05-06

Bath / Wave soldering



Solder paste 07-08

Lead-free / Tin-lead / Die attach



Tin balls 09

99.9% stated purity



SMT red adhesive 09

Single-component epoxy



Soldering flux 09

Low resin / Low halogen

02 / SOLDER WIRE

Lead-free solder wire.

LEAD-FREE



Alloy (wt%)	Melting (°C)	Density (listed)
Sn99.3Cu0.7	227	7.4
Sn99Ag0.3Cu0.7	221	7.37
Sn96.5Ag3.0Cu0.5	217	7.37

Fast wetting

Bright solder joints

Low spatter

No-clean options

FLUX-CORE OPTIONS

R

Rosin

RMA

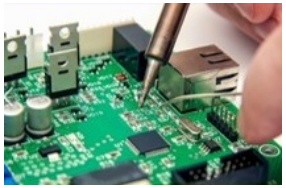
Mildly activated

RA

Activated rosin



Automatic soldering



Hand / capacitor work

For premium electronics and electrical assembly.

Other options: stainless-steel, solid-core, high / low-temperature and nickel-plated wire.

Density unit: confirm at quotation.

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03 / SOLDER WIRE

Tin-lead solder wire.

TIN-LEAD



Grade	Alloy (wt%)	Melting range (°C)	Density (listed)	Diameter (mm)
63A	Sn63Pb37	183	8.4	0.3-3
No. 1	Sn60Pb40	183-190	8.5	0.5-3
No. 2	Sn55Pb45	183-203	8.7	0.5-3
No. 3	Sn50Pb50	183-216	8.9	0.8-3
No. 4	Sn45Pb55	183-227	9.0	0.8-3
No. 5	Sn40Pb60	183-238	9.3	0.8-3
No. 6	Sn35Pb65	183-247	9.5	0.8-3
No. 7	Sn30Pb70	183-255	9.7	0.8-3
No. 8	Sn25Pb75	183-266	9.9	0.8-3

Rosin-core / Automatic / Manual

63A / No. 1 / No. 2

Precision / PCBs / communications

No. 3 / No. 4 / No. 5

Appliances / automotive / hardware

No. 6 / No. 7 / No. 8

Radiators / lamps / cable joints

Density figures are listed as supplied; confirm the applicable unit for the selected grade.

04 / SOLDER BARS

Lead-free solder bars.

LEAD-FREE / PURE TIN



Alloy (wt%)	Melting (°C)	Density (listed)
Sn99.3Cu0.7	227	7.4
Sn99Ag0.3Cu0.7	221	7.37
Sn96.5Ag3.0Cu0.5	217	7.37
Sn99.95 (pure tin)	232	7.41

Sn99.95: PCB electroplating and copper dilution in solder baths.

70-180°C

Low-melting alloys / thermal safety

SAC305 / SAC307

Standard silver-bearing options

Bath / Wave

Anti-oxidation and custom grades

Density figures are listed as supplied; confirm the applicable unit for the selected grade.

05 / SOLDER BARS

Tin-lead solder bars.

TIN-LEAD



For solder-bath and wave processes

Alloy (wt%)	Melting range (°C)	Density (listed)
Sn63Pb37	183	8.4
Sn60Pb40	183-190	8.5
Sn55Pb45	183-203	8.7
Sn50Pb50	183-216	8.9
Sn45Pb55	183-227	9.0
Sn40Pb60	183-238	9.3
Sn35Pb65	183-247	9.5
Sn30Pb70	183-255	9.7
Sn25Pb75	183-266	9.9

Sn63Pb37 - Sn55Pb45

Precision electronics / demanding PCBs

Sn50Pb50 - Sn40Pb60

Appliances / general electrical work

Sn35Pb65 - Sn25Pb75

Mechanical / radiators / cable joints

Density figures are listed as supplied; confirm the applicable unit for the selected grade.

06 / SOLDER PASTE

Lead-free solder paste.

500 g / JAR



Grade	Alloy (wt%)	Listed melt (°C)	Powder (μm)
Low-temp.	Sn42Bi58	138	20-38
Mid-temp.	Sn64.7Bi35Ag0.3	183	20-38
Mid-temp.	Sn64Bi35Ag1	183	20-38
High-temp.	Sn99Ag0.3Cu0.7	217*	20-38

Stable printing

Low slump

0.3 mm pitch

Fine-pitch printing

APPLICATIONS

LED assembly / Demanding electronics

Good wetting / Reduced bridging / Bright joints

* This paste is listed at 217°C; the corresponding wire / bar alloy is listed at 221°C. Confirm the selected grade.

07 / SOLDER PASTE

Tin-lead solder paste.



500 g / JAR

SEMICONDUCTOR PASTE

High-lead die attach / Nitrogen reflow / ~2% residue

Grade	Alloy (wt%)	Listed melt (°C)	Powder (µm)	Application	Key features
55/45 - Type 3	Sn55Pb45	190	25-45	LED	Resists LED displacement
60/40 - Type 3	Sn60Pb40	190	25-45	LED	Bright joints / Reduced bridging
63/37 - Type 3	Sn63Pb37	183	25-45	General SMT	Strong wetting / Bright, full joints
63/37 - Type 4	Sn63Pb37	183	20-38	Fine-pitch	Fine powder / Reduced bridging
Silver / Type 4	Sn62.9Pb36.9Ag0.2	183	20-38	QFN assembly	Fast wetting / Low solder-ball formation / Reliable joints
Higher silver / Type 4	Sn62.8Pb36.8Ag0.4	183	20-38	BGA reballing	Good wetting / Conductivity / Rounded, bright joints

Confirm alloy, powder size and thermal process for the selected grade.

08 / AUXILIARY MATERIALS

Complete the soldering process.

Tin balls

99.9% PURE TIN



- Lead-free
- Good wetting / Low dross
- Clean, bright appearance

SMT red adhesive

HEAT-CURING EPOXY



- Single-component formulation
- Controlled adhesive-dot shape
- Room-temperature storage

Soldering flux

LOW RESIN / LOW HALOGEN



- Minimal post-solder residue
- Good solderability
- Low fumes / Low odor

09 / COMPANY & CONTACT

Materials. Expertise. Supply.

2014 Established	30+ Team members	1,000+ m² Factory area
6 Product lines	RMB 20m+ Manufacturing assets	RMB 100m Annual production value

QUALITY SYSTEMS

ISO 9001:2015 **ISO 14001:2015**

SGS test documentation / MSDS product information

Electronics / LED lighting / Medical equipment
Aerospace / Semiconductor assembly

Vibgyorlighting

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PRODUCT ENQUIRIES

Phone: 0086 15026859051

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Send your alloy, process, size and quantity requirements.